

MOUNTING STRUCTURE OF SEMICONDUCTOR CHIP AND METHOD FOR MOUNTING THE SAME

Publication number: JP2000243765

Publication date: 2000-09-08

Inventor: AZUMA MITSUTOSHI; MIYAGAWA FUMIO

Applicant: SHINKO ELECTRIC IND CO

Classification:

- International: H01L21/56; H01L21/60; H01L21/02; (IPC1-7): H01L21/56; H01L21/60

- European:

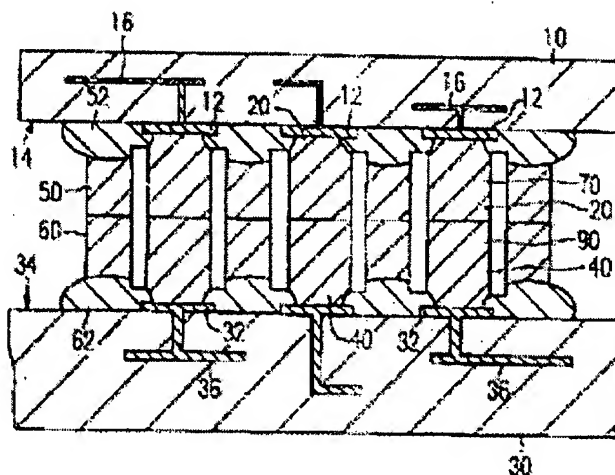
Application number: JP19990040922 19990219

Priority number(s): JP19990040922 19990219

Report a data error here

Abstract of JP2000243765

PROBLEM TO BE SOLVED: To obtain a mounting structure of a semiconductor chip, capable of readily, accurately, and rigidly face-mounting the highly integrated semiconductor chip on a mounting substrate. **SOLUTION:** In this mounting structure, a connection terminal 20 erected in an electrode pad 12 of a semiconductor chip 10 is mutually joined to a connection terminal 40, erected in a conductive pad 32 in a mounting substrate 30 corresponding to the terminal 20. A dummy terminal 50 is erected via an insulated layer 52, on a face 14 positioned between the electrode pads 12 of the semiconductor chip. A dummy terminal 60 is erected via an insulated layer 62, on a face 34 positioned between the conductive pads 32 of the mounting substrate. The dummy terminal 50 at a side of the semiconductor chip 10 is mutually joined to the dummy terminal 60 at a side of the mounting substrate 30 corresponding to the terminal 50. The semiconductor chip 10 is rigidly joined to the mounting substrate 30 via the dummy terminals 50, 60 and the insulated layers 52, 62.



Data supplied from the esp@cenet database - Worldwide